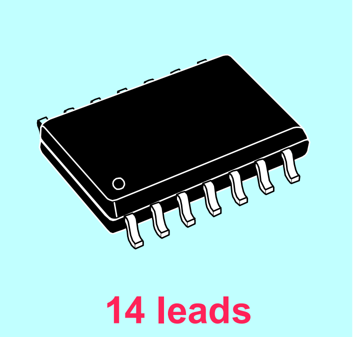
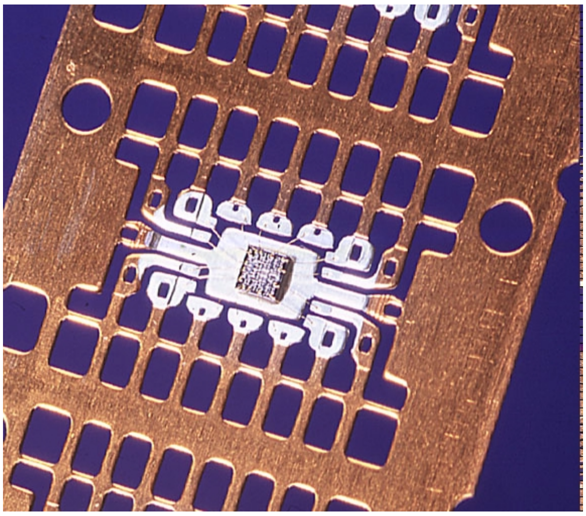
Thermal Data

SO 14



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.20 mm	2.61 W/cm°C
die attach	epoxy glue (silver filler)	10-40 µm	0.01 W/cm°C
molding compound	epoxy resin	1.65 mm	0.0063W/cm°C

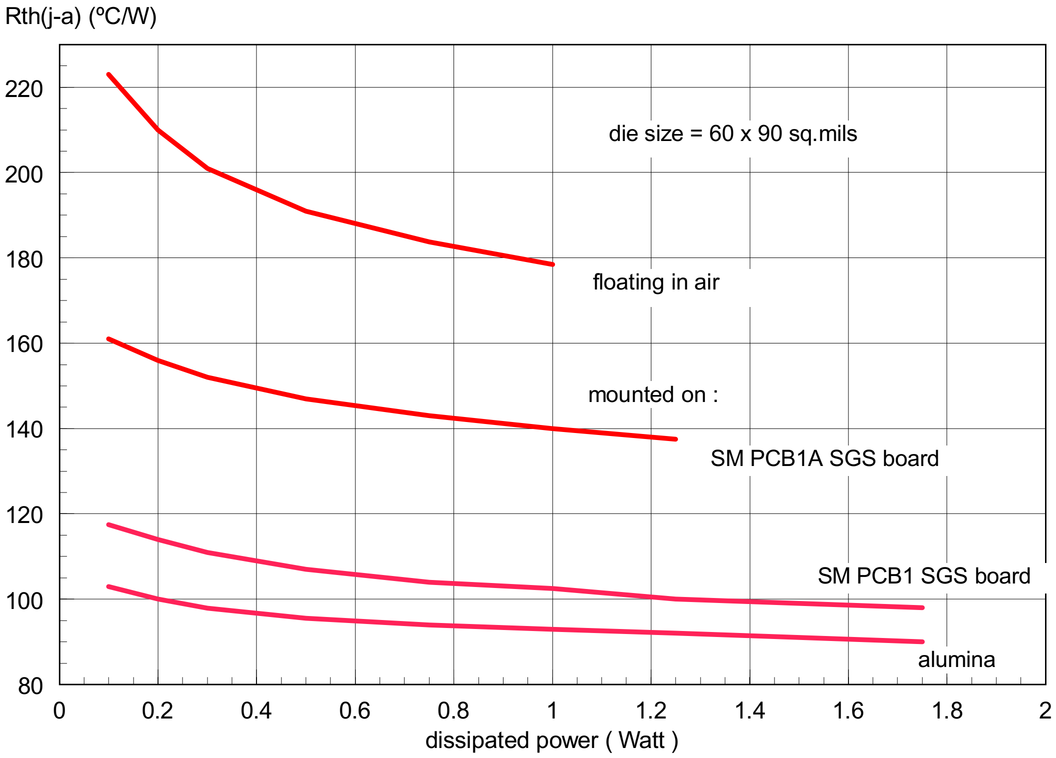


Charts enclosed :

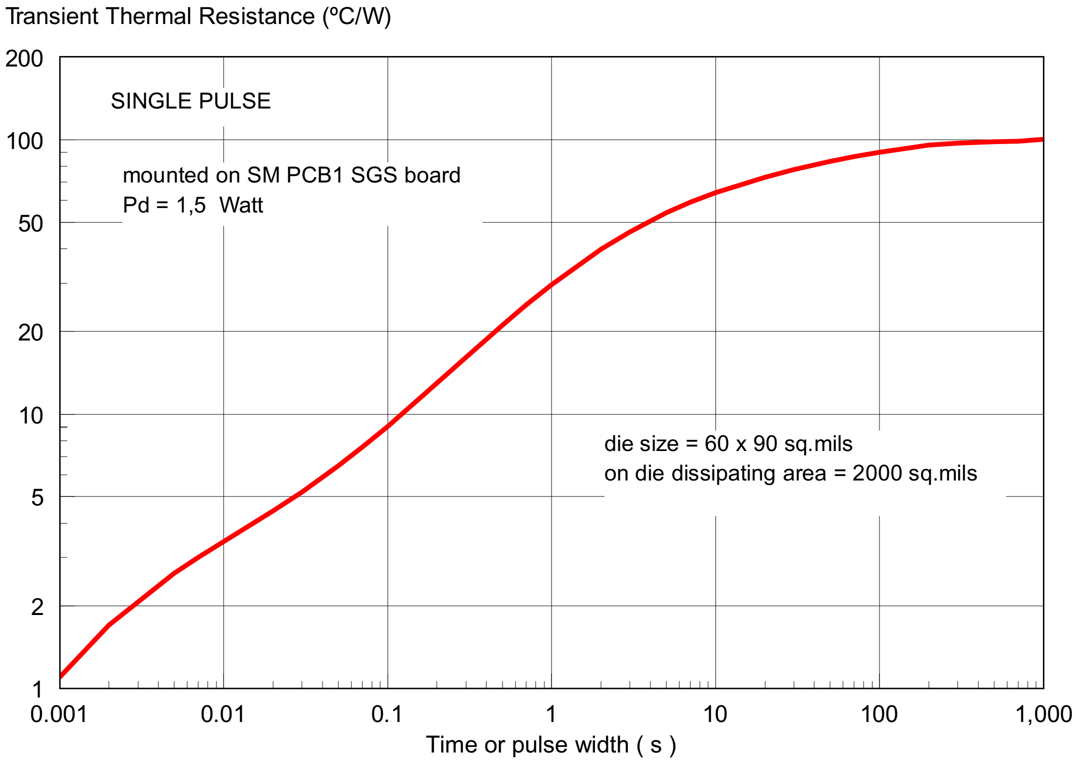
1) Rth(j-a) vs power dissipation

2) Zth(j-a) vs time width and die size

1)


Rth(j-a) (ºC/W)
220
200
180
160
140
120
100
80
0
0.2
0.4
0.6
0.8
1
1.2
1.4
1.6
1.8
2
dissipated power (Watt)
die size = 60 x 90 sq.mils
floating in air
mounted on :
SM PCB1A SGS board
SM PCB1 SGS board
alumina

2)


Transient Thermal Resistance (ºC/W)
200
100
50
20
10
5
2
1
0.001
0.01
0.1
1
10
100
1,000
Time or pulse width (s)
SINGLE PULSE
mounted on SM PCB1 SGS board
Pd = 1,5 Watt
die size = 60 x 90 sq.mils
on die dissipating area = 2000 sq.mils